

11-09-1998

FLH Ref. No.: 450100-4577



100872721

F

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

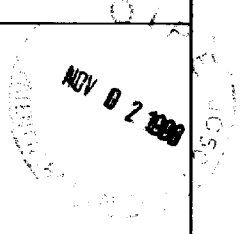
MRO 11/2/98

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies)
 Toshiyuki NAKAGAWA, Yoshihide SHINPUKU
 Additional name(s) of conveying party(ies) attached?
 ___ Yes X No

2. Name and address of receiving party(ies)
 Name: SONY CORPORATION
 7-35 Kitashinagawa 6-chome
 Shinagawa-Ku, Tokyo 100-31, Japan
 Additional name(s) & address(es) attached? ___ Yes x No

3. Nature of conveyance:
X Assignment
 ___ Security Agreement
 ___ Merger
 ___ Change of Name
 ___ Other
 Execution Date(s): October 13, and October 12, 1998.



4. Application number(s) or patent number(s):
 If this document is being filed together with a new application, the execution date of the application is:
 A. Patent Application No.(s) 09/150,397 filed September 9, 1998
 Additional numbers attached? ___ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: WILLIAM S. FROMMER
 Internal Address: FROMMER LAWRENCE & HAUG LLP
 Street Address: 745 FIFTH AVENUE
 City: NEW YORK State: N.Y. Zip: 10151

6. Total number of applications and patents involved 1
 7. Total fee (37 CFR 3.41) \$ 40.00
X Enclosed
 ___ Authorized to be charged to deposit account 50-0320
 8. Deposit account number:
 (Attach duplicate copy of this page if paying by deposit account)

Do not use this space

9. Statement and signature.
 To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Gordon Kessler
 for WILLIAM S. FROMMER
 Name of Person Signing
[Signature]
 Signature
 October 29, 1998
 Date
 Total number of pages including cover sheet, attachments, and document: 2

Do not detach this portion

Documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

825 P 075 / 0500

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

MODULATING DEVICE, MODULATING DEVICE, DEMODULATING DEVICE, DEMODULATING DEVICE, AND TRANSMISSION MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/150.397, Filing Date: September 9, 1998.

This assignment executed on the dates indicated below.

Toshiyuki NAKAGAWA Oct, 13, 1998
Name of first or sole inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor
Toshiyuki Nakagawa Oct, 13, 1998
Signature of first or sole inventor Date of this assignment

Yoshihide SHINPUKU Oct. 12. 1998
Name of second inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor
Yoshihide Shimpuku Oct. 12. 1998
Signature of second inventor Date of this assignment

Name of third inventor Execution date of U.S. Patent Application

Residence of third inventor

Signature of third inventor Date of this assignment